

LTF AND LTH SERIES

● FEATURES

- STANDARD 8 AND 14 DIP PACKAGE
- TOLERANCE AND STABILITY TO ± 25 PPM
- LOW COST
- AVAILABLE IN 3.3 VOLT

● SPECIFICATIONS

SERIES		LTF	LTH
PACKAGE		14 PIN DIP	8 PIN DIP
FREQUENCY RANGE		500.00KHz TO 125.00MHz	500.00KHz TO 125.00MHz
FREQUENCY STABILITY †		LTF 100 Co1100: ± 100 ppm	LTH 13100 : ± 100 ppm
		LTF 50 Co1050: ± 50 ppm	LTF 13150 : ± 50 ppm
		LTF 50 Co1025: ± 25 ppm	LTF 13025 : ± 25 ppm
OPERATING TEMPERATURE RANGE		0 TO + 70 STANDARD -40 TO +85 EXTENDED	0 TO + 70 STANDARD -40 TO +85 EXTENDE
STORAGE TEMPERATURE RANGE		-55 TO +125	-55 TO +125
INPUT	VOLTAGE ††	+5 VDC \pm 0.5VDC	+5 VDC \pm 0.5VDC
	CURRENT (MAX)	500.00KHz TO 2.999MHz:30mA	500.00KHz TO 2.999MHz:30mA
		3.00KHz TO 31.999MHz:50mA	3.00KHz TO 31.999MHz:50mA
		32.00KHz TO 79.999MHz:70mA	32.00KHz TO 79.999MHz:70mA
		80.00KHz TO 125.00MHz:80mA	80.00KHz TO 125.00MHz:80mA
OUTPUT	SYMMETRY (AT 1.4 VDC LEVEL)	40 TO 60% NORMAL 45 TO 55% TIGHT	40 TO 60% NORMAL 45 TO 55% TIGHT
	RISE AND FALL TIME (0.4-2.4 VDC)	UNDER 9 MHz: ± 15 ns MAX	UNDER 9 MHz: ± 15 ns MAX
		9 MHz TO 32 MHz: ± 10 ns MAX	9 MHz TO 32 MHz: ± 10 ns MAX
		32 MHz TO 80 MHz: ± 6 ns MAX	32 MHz TO 80 MHz: ± 6 ns MAX
		80MHz TO 125 MHz: ± 4 ns MAX	80MHz TO 125 MHz: ± 4 ns MAX
	LOGIC "0"LEVEL	+0.5 V MAX,SINK TO 16 mA	+0.5 V MAX,SINK TO 16 mA
	LOGIC "1"LEVEL	+2.4 V MIN,SOURCE 0.4mA	+2.4 V MIN,SOURCE 0.4mA
LOAD	1 TO 10 TTL STANDARD	1 TO 10 TTL STANDARD	

†FREQUENCY STABILITY INCLUSIVE OF ROOM TOLERANCE

FREQUENCY STABILITY OVER TEMPERATURE,10% POWER SUPPLY VARIATION,AGING,SHOCK,AND VIBRATION

††+3.3 VOTL VERSION IS AVAILABLE.CONSULT RALTRON FOR SPECIFICATIONS

†††OUTPUT LOADS ALSO AVAILABLE AT 15Pf AND 50PF,CONSULT RALTRON FOR SPECIFICATIONS

● PART NUMBERING SYSTEM

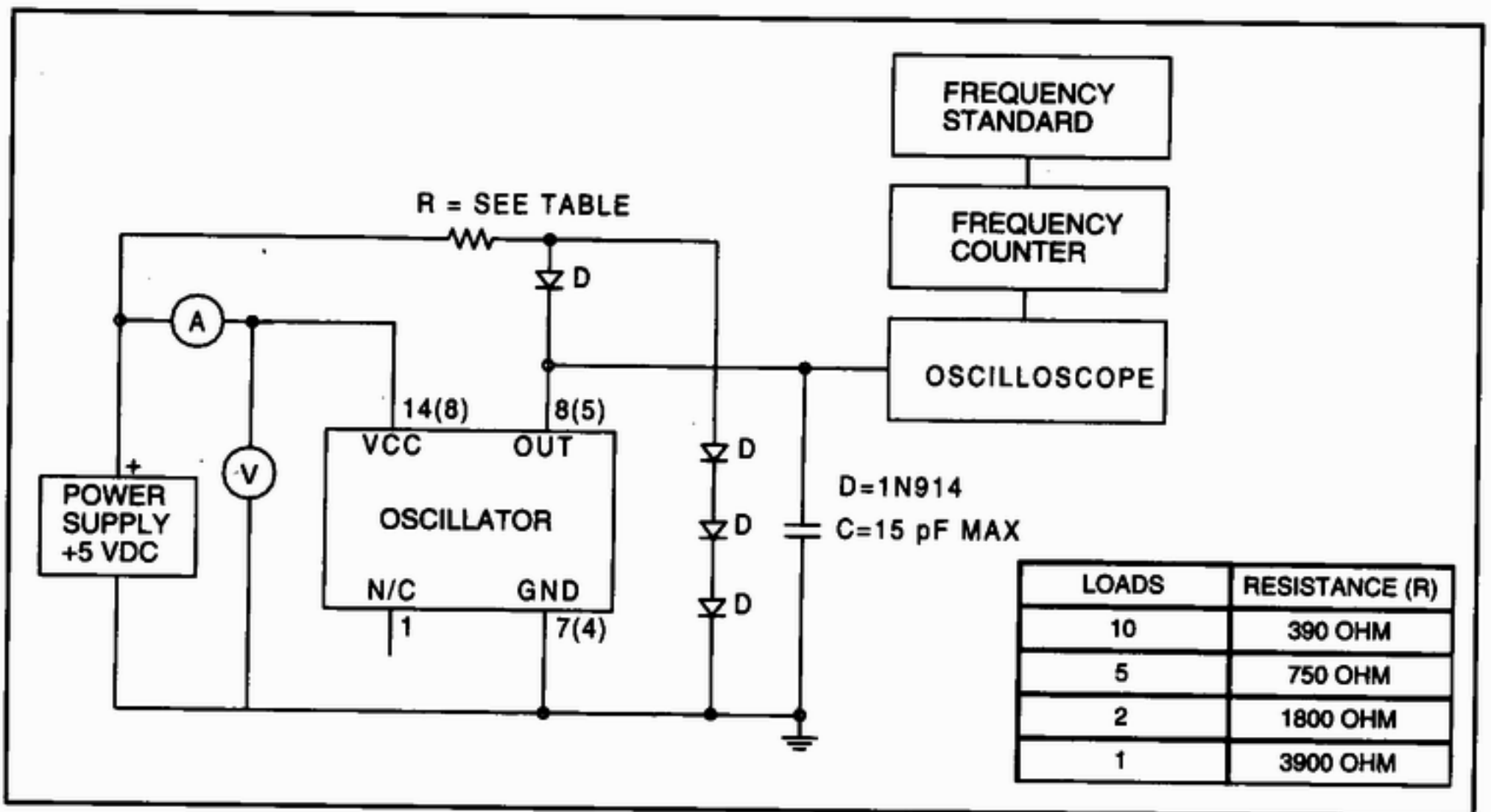
SERIES		FREQUENCY STABILITY		FREQUENCY	EXTENDED TEMPERATURE	SYMMETRY		OPTIONS	
LTF	(14 PIN DIP)	100	± 100 PPM	IN MHz	EXT	T	TIGHT SYMMETRY	TR	TAPE AND REEL
LTH	(8 PIN DIP)	50	± 50 PPM					GW	GULL WING
		25	± 25 PPM					3.3V	+3.3V

EXAMPLE:LTF 100-20.000-EXT-T,LTH50-32.000-T-TR

● ENVIRONMENTAL AND TECHNICAL CONDITIONS

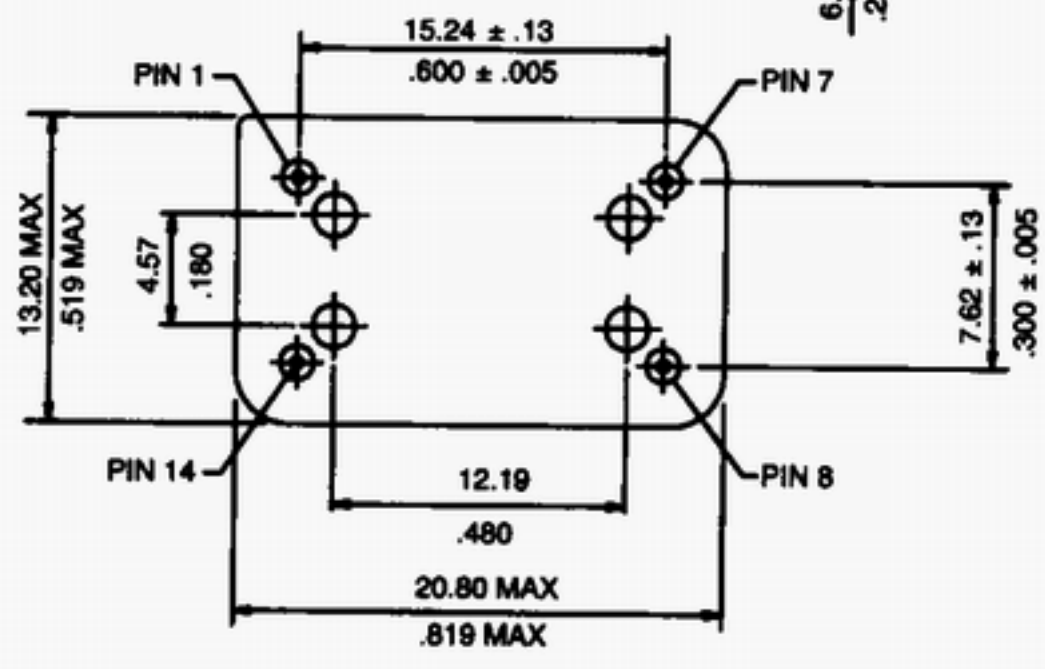
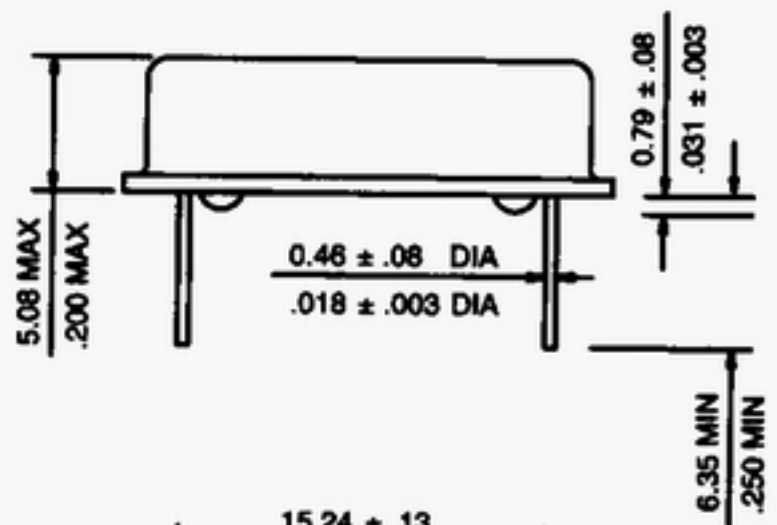
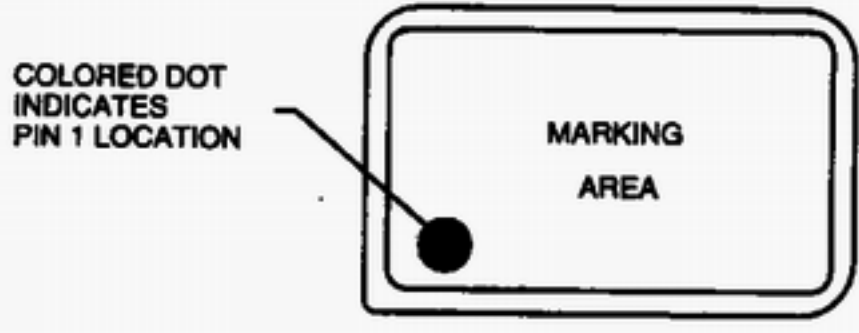
ENVIRONMENTAL	
TEMPERATURE CYCLE	MIL-STD 883,METHOD 1010, 10 CYCLES-20 TO 85
SHOCK	MIL-STD-202,METHOD 213,TEST CONDITION C
VIBRATION	MIL-STD-202,METHOD 204,TEST CONDITION A
RESISTANCE TO SOLDERING HEAT	MIL-STD-202,METHOD 210,TEST CONDITION B
HUMIDITY	85% RELATIVE HUMIDITY AT 85 250 HOURS
MECHANICAL	
GROSS LEAK TEST	MIL-STD-883,METHOD 1014,TEST CONDITION C
FINE LEAK TEST	MIL-STD-883,METHOD 1014,TEST CONDITION A
TERMINAL STRENGTH	MIL-STD-202,METHOD 211,TEST CONDITION A AND C
MARKING INK	EPOXY,HEAT CURED.
MOISTURE RESISTANCE	MIL-STD-202,METHOD 106,OMIT STEP 7B
SOLDERABILITY	MIL-STD-202,METHOD 208,95% COVERAGE
SOLVENT RESISTANCE	MIL-STD-202,METHOD 2020,METHOD 215

● TEST CIRCUIT



● OUTLINE DRAWINGS

LTF PACKAGE (FULL SIZE 14 PIN DIP) Scale none Dimension in $\frac{\text{Mm}}{\text{inch}}$



PIN CONNECTION

PIN	FUNCTION
1	N/C
7	GROUND
8	OUTPUT
14	VCC

NOTE: PIN 7 IS INTERNAL TO HEADER